# **Switching Transistor**

## **PNP Silicon**

#### **Features**

• Pb-Free Package is Available

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector - Emitter Voltage	$V_{CEO}$	-40	Vdc
Collector - Base Voltage	$V_{CBO}$	-40	Vdc
Emitter – Base Voltage	$V_{EBO}$	-5.0	Vdc
Collector Current – Continuous	I <sub>C</sub>	-600	mAdc

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1)  T <sub>A</sub> = 25°C	P <sub>D</sub>	225	mW
Derate above 25°C		1.8	mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate, (Note 2)	P <sub>D</sub>	300	mW
T <sub>A</sub> = 25°C Derate above 25°C		2.4	mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

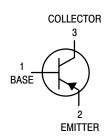
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

- 1.  $FR-5 = 1.0 \times 0.75 \times 0.062$  in.
- 2. Alumina =  $0.4 \times 0.3 \times 0.024$  in. 99.5% alumina.



## ON Semiconductor®

#### http://onsemi.com





SOT-23 (TO-236) CASE 318-08 STYLE 6

#### **MARKING DIAGRAM**



2T = Specific Device Code D = Date Code

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

## **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic		Symbol	Min	Max	Unit
OFF CHARACTERISTICS					
Collector – Emitter Breakdown Voltage (Note (I <sub>C</sub> = -1.0 mAdc, I <sub>B</sub> = 0)	e 3)	V <sub>(BR)CEO</sub>	-40	_	Vdc
Collector – Base Breakdown Voltage (I <sub>C</sub> = -0.1 mAdc, I <sub>E</sub> = 0)		V <sub>(BR)CBO</sub>	-40	_	Vdc
Emitter-Base Breakdown Voltage $(I_E = -0.1 \text{ mAdc}, I_C = 0)$	V <sub>(BR)EBO</sub>	-5.0	_	Vdc	
Base Cutoff Current $(V_{CE} = -35 \text{ Vdc}, V_{EB} = -0.4 \text{ Vdc})$	I <sub>BEV</sub>	_	-0.1	μAdc	
Collector Cutoff Current (V <sub>CE</sub> = -35 Vdc, V <sub>EB</sub> = -0.4 Vdc)	I <sub>CEX</sub>	_	-0.1	μAdc	
ON CHARACTERISTICS		·	•	•	•
$\begin{array}{l} \text{DC Current Gain} \\ \text{(I}_{C} = -0.1 \text{ mAdc, V}_{CE} = -1.0 \text{ Vdc)} \\ \text{(I}_{C} = -1.0 \text{ mAdc, V}_{CE} = -1.0 \text{ Vdc)} \\ \text{(I}_{C} = -10 \text{ mAdc, V}_{CE} = -1.0 \text{ Vdc)} \\ \text{(I}_{C} = -150 \text{ mAdc, V}_{CE} = -2.0 \text{ Vdc)} \\ \text{(I}_{C} = -500 \text{ mAdc, V}_{CE} = -2.0 \text{ Vdc)} \\ \text{(Note)} \end{array}$	,	h <sub>FE</sub>	30 60 100 100 20	- - - 300 -	-
Collector – Emitter Saturation Voltage (Note 3) ( $I_C = -150 \text{ mAdc}$ , $I_B = -15 \text{ mAdc}$ ) ( $I_C = -500 \text{ mAdc}$ , $I_B = -50 \text{ mAdc}$ )		V <sub>CE(sat)</sub>	_ _	-0.4 -0.75	Vdc
Base – Emitter Saturation Voltage (Note 3) ( $I_C = -150$ mAdc, $I_B = -15$ mAdc) ( $I_C = -500$ mAdc, $I_B = -50$ mAdc)		V <sub>BE(sat)</sub>	-0.75 -	-0.95 -1.3	Vdc
SMALL-SIGNAL CHARACTERISTICS					
Current – Gain — Bandwidth Product $(I_C = -20 \text{ mAdc}, V_{CE} = -10 \text{ Vdc}, f = 100 \text{ I})$	MHz)	f <sub>T</sub>	200	_	MHz
Collector–Base Capacitance $(V_{CB} = -10 \text{ Vdc}, I_E = 0, f = 1.0 \text{ MHz})$		C <sub>cb</sub>	-	8.5	pF
Emitter–Base Capacitance $(V_{BE} = -0.5 \text{ Vdc}, I_{C} = 0, f = 1.0 \text{ MHz})$		C <sub>eb</sub>	-	30	pF
Input Impedance ( $I_C = -1.0 \text{ mAdc}$ , $V_{CE} = -10 \text{ Vdc}$ , $f = 1.0 \text{ kHz}$ )		h <sub>ie</sub>	1.5	15	kΩ
Voltage Feedback Ratio ( $I_C = -1.0 \text{ mAdc}$ , $V_{CE} = -10 \text{ Vdc}$ , $f = 1.0 \text{ kHz}$ )		h <sub>re</sub>	0.1	8.0	X 10 <sup>-4</sup>
Small – Signal Current Gain ( $I_C = -1.0$ mAdc, $V_{CE} = -10$ Vdc, $f = 1.0$ kHz)		h <sub>fe</sub>	60	500	-
Output Admittance ( $I_C = -1.0 \text{ mAdc}$ , $V_{CE} = -10 \text{ Vdc}$ , $f = 1.0 \text{ kHz}$ )		h <sub>oe</sub>	1.0	100	μmhos
SWITCHING CHARACTERISTICS		<del>-</del>			
Delay Time	$(V_{CC} = -30 \text{ Vdc}, V_{EB} = -2.0 \text{ Vdc},$	t <sub>d</sub>	-	15	
Rise Time	$I_C = -150 \text{ mAdc}, I_{B1} = -15 \text{ mAdc})$	t <sub>r</sub>	_	20	ns
Storage Time	$(V_{CC} = -30 \text{ Vdc}, I_{C} = -150 \text{ mAdc},$	t <sub>s</sub>	<u> </u>	225	ne
Fall Time	$I_{B1} = I_{B2} = -15 \text{ mAdc}$	t <sub>f</sub>	-	30	ns

<sup>3.</sup> Pulse Test: Pulse Width  $\leq$  300  $\mu\text{s},$  Duty Cycle  $\leq$  2.0%.

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MMBT4403LT1	SOT-23 (TO-236)	3000 Tape & Reel
MMBT4403LT1G	SOT-23 (TO-236) (Pb-Free)	3000 Tape & Reel
MMBT4403LT3	SOT-23 (TO-236)	10,000 Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

## **SWITCHING TIME EQUIVALENT TEST CIRCUIT**

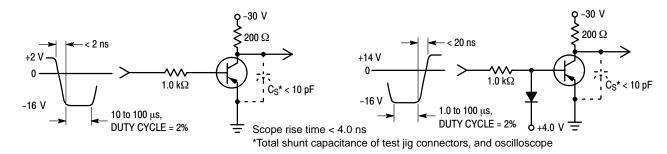


Figure 1. Turn-On Time

Figure 2. Turn-Off Time

## TRANSIENT CHARACTERISTICS

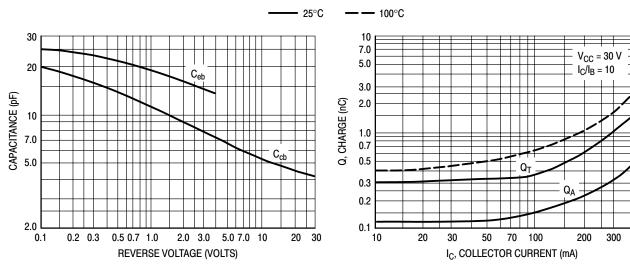


Figure 3. Capacitances

Figure 4. Charge Data

500

300

500

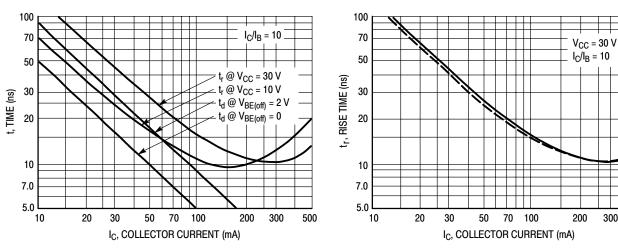


Figure 5. Turn-On Time

Figure 6. Rise Time

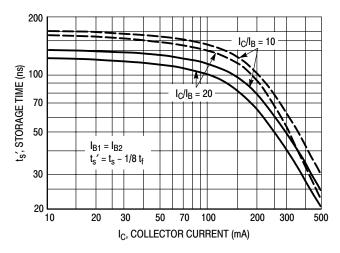
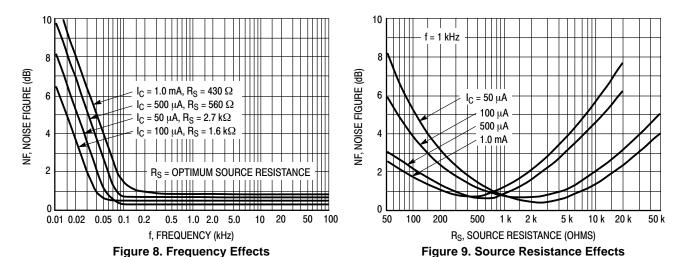


Figure 7. Storage Time

#### SMALL-SIGNAL CHARACTERISTICS NOISE FIGURE

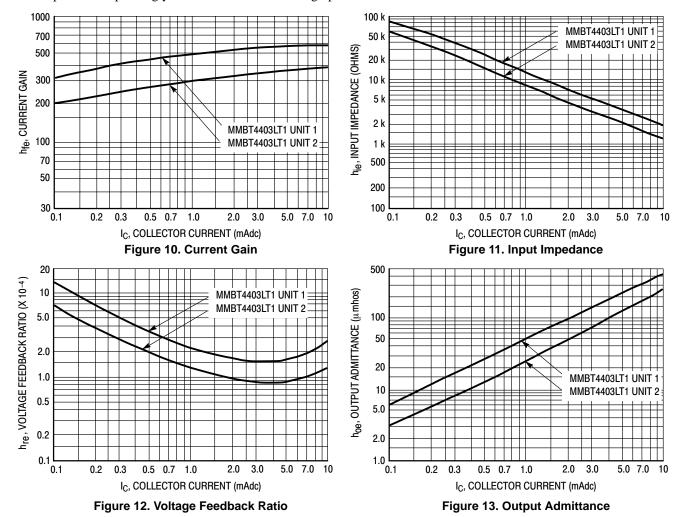
 $V_{CE} = -10 \text{ Vdc}$ ,  $T_A = 25^{\circ}\text{C}$ ; Bandwidth = 1.0 Hz



## h PARAMETERS

 $V_{CE} = 10 \text{ Vdc}, f = 1.0 \text{ kHz}, T_A = 25^{\circ}\text{C}$ 

This group of graphs illustrates the relationship between  $h_{fe}$  and other "h" parameters for this series of transistors. To obtain these curves, a high–gain and a low–gain unit were selected from the MMBT4403LT1 lines, and the same units were used to develop the correspondingly numbered curves on each graph.



#### STATIC CHARACTERISTICS

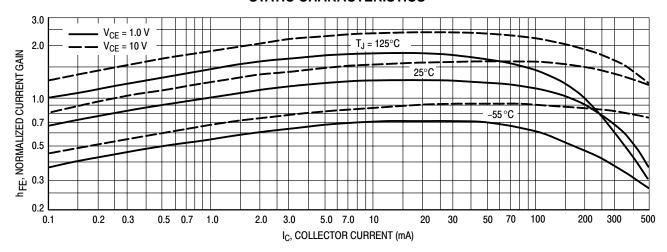


Figure 14. DC Current Gain

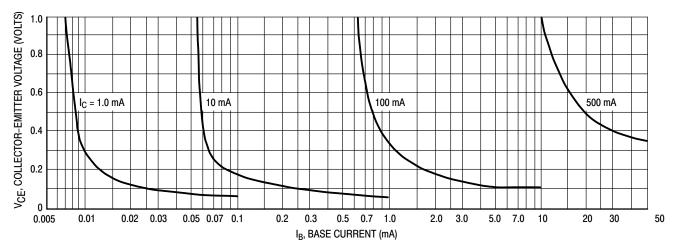


Figure 15. Collector Saturation Region

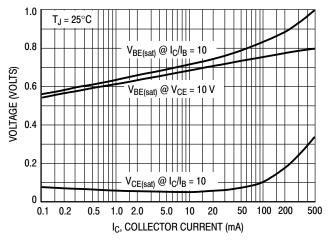
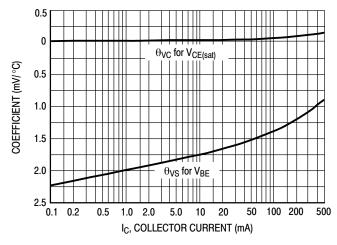


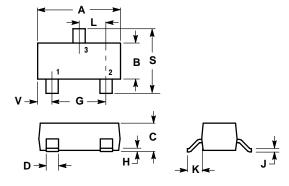
Figure 16. "On" Voltages



**Figure 17. Temperature Coefficients** 

#### **PACKAGE DIMENSIONS**

**CASE 318-08** SOT-23 (TO-236) **ISSUE AH** 



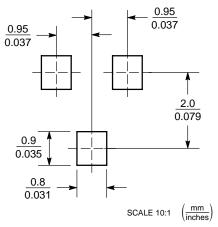
NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATEDIAL
- MATERIAL.
  4. 318-03 AND -07 OBSOLETE, NEW STANDARD 318-08.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.1102	0.1197	2.80	3.04
В	0.0472	0.0551	1.20	1.40
C	0.0350	0.0440	0.89	1.11
D	0.0150	0.0200	0.37	0.50
G	0.0701	0.0807	1.78	2.04
Н	0.0005	0.0040	0.013	0.100
J	0.0034	0.0070	0.085	0.177
K	0.0140	0.0285	0.35	0.69
L	0.0350	0.0401	0.89	1.02
S	0.0830	0.1039	2.10	2.64
٧	0.0177	0.0236	0.45	0.60

- STYLE 6:
  PIN 1. BASE
  2. EMITTER
  3. COLLECTOR

#### **SOLDERING FOOTPRINT\***



SOT-23

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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